

# Global Semiconductor Silicon Wafer Market

<https://marketpublishers.com/r/G7C78484C6F2EN.html>

Date: October 2019

Pages: 163

Price: US\$ 1,375.00 (Single User License)

ID: G7C78484C6F2EN

## Abstracts

### REPORT SCOPE:

This report forecasts the market for compound semiconductor wafers for 2018-2023. The report presents the market forecast in terms of dollar value (\$ million) and shipment volume (msi).

Dollar value and shipment volume are broken down along the following end uses -

Telecommunications.

Instrumentation and scientific research.

Healthcare.

Energy, defense and surveillance.

Computing and entertainment.

Industrial and automotive.

Retail and others.

Each of the end applications is further broken down by crystal growth methods -

Bridgman and allied methods (Bridgman).

Float-zone (FZ).

Czochralski (CZ) and allied methods (Czochralski).

Each end application is broken down by the following wafer-bonding methods -

Direct bonding.

Surface-activated bonding.

Anodic bonding.

Plasma bonding.

Each end application is further broken down by node size -

10 nm and lower.

12 to 22 nm.

28 nm and above.

Each end-application is further broken down by regional market -

Americas.

Europe, Middle East and Africa (EMEA).

Asia Pacific (APAC).

## **REPORT INCLUDES:**

72 data tables and 10 additional tables

An overview of the global markets for semiconductor silicon wafers

Analyses of global market trends, with data from 2017, 2018, and projections of compound annual growth rates (CAGRs) through 2023

Identification of potential applications of semiconductor silicon wafers in consumer electronics, telecommunications, automotive, defence, and healthcare industry

Overview of various bonding technologies in the semiconductor silicon wafers industry, including direct bonding, surface activated bonding, plasma activated bonding and anodic bonding

Coverage of major innovation initiatives in silicon wafer fabrication technology

Detailed analysis of major vendors and suppliers of the industry, including 3M, Global Wafers Co., Ltd., Mechatronik Systemtechnik GmbH, Nissan Chemical Corporation, Samsung, Shanghai Simgui Technology, Toshiba and Wafer World Inc

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Foundries and Semiconductor Device Designers

Pricing Dynamics

Key Companies

Companies

3M

II-VI EPIWORKS

AIXTRON

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ALINEASON

BREWER SCIENCE INC.

CMK SRO

DISCO CORP.

ELECTRONICS AND MATERIALS CORP. LTD (E&M)

ELKEM

EV GROUP



GLOBALWAFERS JAPAN CO. LTD.  
HEMLOCK SEMICONDUCTOR CORP.  
KOKUSAI ELECTRIC  
INTEL  
LINTEC CORP.  
MECHATRONIK SYSTEMTECHNIK GMBH  
MICRON  
NICHIA CORP.  
NISSAN CHEMICAL CORP.  
OKMETIC  
POWERCHIP  
SAMSUNG  
SHANGHAI SIMGUI TECHNOLOGY  
SHIN-ETSU CHEMICAL CO. LTD.  
SILTRONIX SILICON TECHNOLOGIES  
SILICON MATERIALS INC.  
SILICON VALLEY MICROELECTRONICS  
SILTRONIC AG  
SK HYNIX  
SK SILTRON  
SOITEC  
SUMCO CORP.  
SUSS MICRO TEC AG  
SYNOVA  
THERMCRAFT  
TOKUYAMA CORP.  
TOSHIBA  
TSMC  
ULVAC INC.  
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